

OSRAM GW PUSTA1.EM

Datasheet

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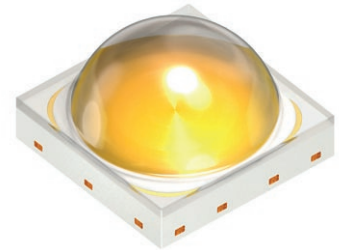
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OSCONIQ® P 3737 (3W)

GW PUSTA1.EM

High-power LED with high performance, superior robustness and long lifetime.



Applications

- Agriculture & Horticulture
- Entertainment
- Indoor Lighting
- Outdoor & Industrial Lighting

Features

- Package: New SMD epoxy package with silicone lens
- Typ. Radiation: 120° (Lambertian emitter)
- Color temperature: 2700K - 5700K
- CRI: 80 (min.), 83 (typ.), R9: 0 (min.)
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)
- Luminous Flux: typ. 424 lm @ 3000 K, 85 °C
- Luminous efficacy: typ. 146 lm/W @ 3000 K, 85 °C

Ordering Information

Type	Color temperature	Luminous Flux ¹⁾ $I_F = 1050 \text{ mA}$ Φ_V	Ordering Code
GW PUSTA1.EM-NANC-XX58-1	2700 K	380 ... 440 lm	Q65112A5872
GW PUSTA1.EM-NBPB-XX57-1	3000 K	400 ... 520 lm	Q65112A8634
GW PUSTA1.EM-NBND-XX56-1	3500 K	400 ... 460 lm	Q65112A5876
GW PUSTA1.EM-NCPA-XX55-1	4000 K	420 ... 500 lm	Q65113A6467
GW PUSTA1.EM-NCPC-XX53-1	5000 K	420 ... 540 lm	Q65112A8631
GW PUSTA1.EM-NCPC-XX52-1	5700 K	420 ... 540 lm	Q65112A8630

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min.	-40 °C
		max.	135 °C
Storage Temperature	T_{stg}	min.	-40 °C
		max.	135 °C
Junction Temperature	T_j	max.	150 °C
Forward Current $T_j = 85\text{ °C}$	I_F	min.	200 mA
		max.	3000 mA
Surge Current $t \leq 10\text{ }\mu\text{s}$; $D = 0.005$; $T_j = 85\text{ °C}$	I_{FS}	max.	4000 mA
Reverse voltage ²⁾	V_R	Not designed for reverse operation	
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V_{ESD}	8 kV	

Characteristics

 $I_F = 1050 \text{ mA}$; $T_J = 85 \text{ }^\circ\text{C}$

Parameter	Symbol		Values
Viewing angle at 50% I_V	2ϕ	typ.	120°
Forward Voltage ³⁾ $I_F = 1050 \text{ mA}$	V_F	min.	2.60 V
		typ.	2.75 V
		max.	3.10 V
Reverse current ²⁾	I_R		Not designed for reverse operation
Color Rendering Index ⁴⁾ (2700K - 5700K)	CRI	min.	80
		typ.	83
Color Rendering Index (R9) ⁴⁾	CRI (R9)	min.	0
Electrical thermal resistance junction/solderpoint with efficiency $\eta_e = 37 \%$	$R_{thJS \text{ elec.}}$	typ.	2.0 K / W

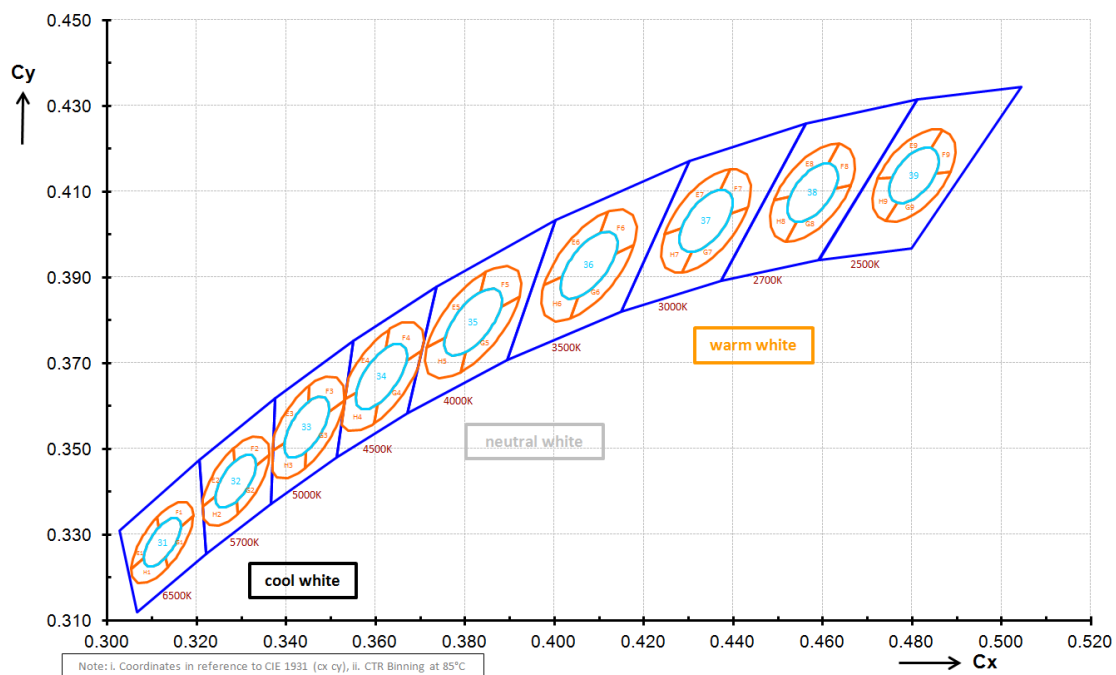
Brightness Groups

Group	Luminous Flux ¹⁾ $I_F = 1050 \text{ mA}$ min. Φ_V	Luminous Flux ¹⁾ $I_F = 1050 \text{ mA}$ max. Φ_V
NA	380 lm	400 lm
NB	400 lm	420 lm
NC	420 lm	440 lm
ND	440 lm	460 lm
NE	460 lm	480 lm
PA	480 lm	500 lm
PB	500 lm	520 lm
PC	520 lm	540 lm

Forward Voltage Groups

Group	Forward Voltage ³⁾ $I_F = 1050 \text{ mA}$ min. V_F	Forward Voltage ³⁾ $I_F = 1050 \text{ mA}$ max. V_F
K1	2.60 V	2.70 V
K2	2.70 V	2.80 V
L1	2.80 V	2.90 V
L2	2.90 V	3.00 V
M1	3.00 V	3.10 V

Chromaticity Coordinate Groups ⁵⁾



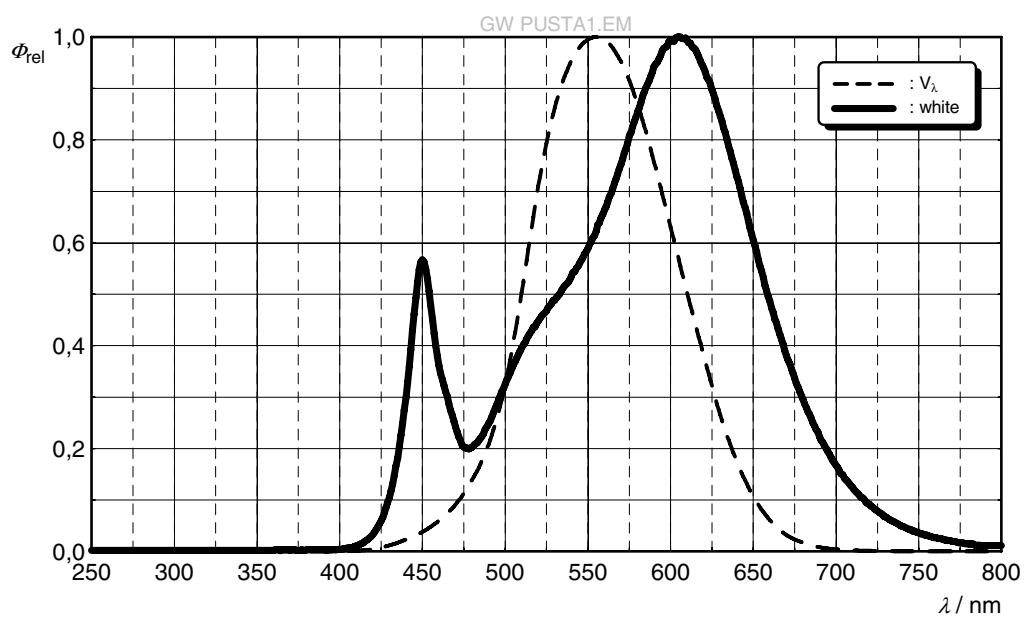
Chromaticity Coordinate Groups

CCT	Center Cx	Center Cy	3step a	3step b	5step a	5step b	Ø
2700 K	0.4577	0.4098	0.008	0.0041	0.0133	0.0068	54.1
3000 K	0.4339	0.4032	0.0086	0.0042	0.0142	0.0069	53.7
3500 K	0.4077	0.3929	0.0093	0.0042	0.0155	0.0069	53.9
4000 K	0.3818	0.3796	0.0094	0.0041	0.0157	0.0068	53.4
5000 K	0.3446	0.3551	0.0081	0.0035	0.0135	0.0059	59.8
5700 K	0.3287	0.3425	0.0072	0.0032	0.0119	0.0052	58.8

CCT	Group	1		2		3		4		5	
		Cx	Cy	Cx	Cy	Cx	Cy	Cx	Cy	Cx	Cy
2700 K	E	0.4637	0.4212	0.4491	0.4081	0.4526	0.4088	0.4613	0.4166		
	F	0.4637	0.4212	0.4663	0.4115	0.4628	0.4108	0.4613	0.4166		
	G	0.4663	0.4115	0.4517	0.3984	0.4541	0.4030	0.4628	0.4108		
	H	0.4541	0.4030	0.4526	0.4088	0.4491	0.4081	0.4517	0.3984		
3000 K	E	0.4393	0.4153	0.4246	0.4002	0.4283	0.4014	0.4371	0.4105		
	F	0.4393	0.4153	0.4432	0.4062	0.4395	0.4050	0.4371	0.4105		
	G	0.4432	0.4062	0.4285	0.3911	0.4307	0.3960	0.4395	0.4050		
	H	0.4307	0.3960	0.4283	0.4014	0.4246	0.4002	0.4285	0.3911		
3500 K	E	0.4118	0.4054	0.3977	0.3883	0.4017	0.3902	0.4102	0.4004		
	F	0.4118	0.4054	0.4177	0.3975	0.4137	0.3957	0.4102	0.4004		
	G	0.4177	0.3975	0.4036	0.3804	0.4052	0.3854	0.4137	0.3957		
	H	0.4052	0.3854	0.4017	0.3902	0.3977	0.3883	0.4036	0.3804		
4000 K	E	0.3845	0.3913	0.3714	0.3737	0.3756	0.3760	0.3834	0.3866		
	F	0.3845	0.3913	0.3922	0.3855	0.3880	0.3832	0.3834	0.3866		
	G	0.3922	0.3855	0.3791	0.3679	0.3802	0.3726	0.3880	0.3832		
	H	0.3802	0.3726	0.3756	0.3760	0.3714	0.3737	0.3791	0.3679		
5000 K	E	0.3451	0.3648	0.3372	0.3528	0.3371	0.3496	0.3396	0.3514	0.3449	0.3609
	F	0.3451	0.3648	0.3530	0.3612	0.3496	0.3588	0.3449	0.3609		
	G	0.3530	0.3612	0.3441	0.3454	0.3443	0.3493	0.3496	0.3588		
	H	0.3443	0.3493	0.3396	0.3514	0.3371	0.3496	0.3369	0.3445	0.3441	0.3454
5700 K	E	0.3283	0.3502	0.3212	0.3373	0.3213	0.3365	0.3242	0.3388	0.3284	0.3471
	F	0.3283	0.3502	0.3363	0.3486	0.3332	0.3462	0.3284	0.3471		
	G	0.3363	0.3486	0.3291	0.3348	0.3290	0.3379	0.3332	0.3462		
	H	0.3291	0.3348	0.3215	0.3337	0.3213	0.3365	0.3242	0.3388	0.3290	0.3379

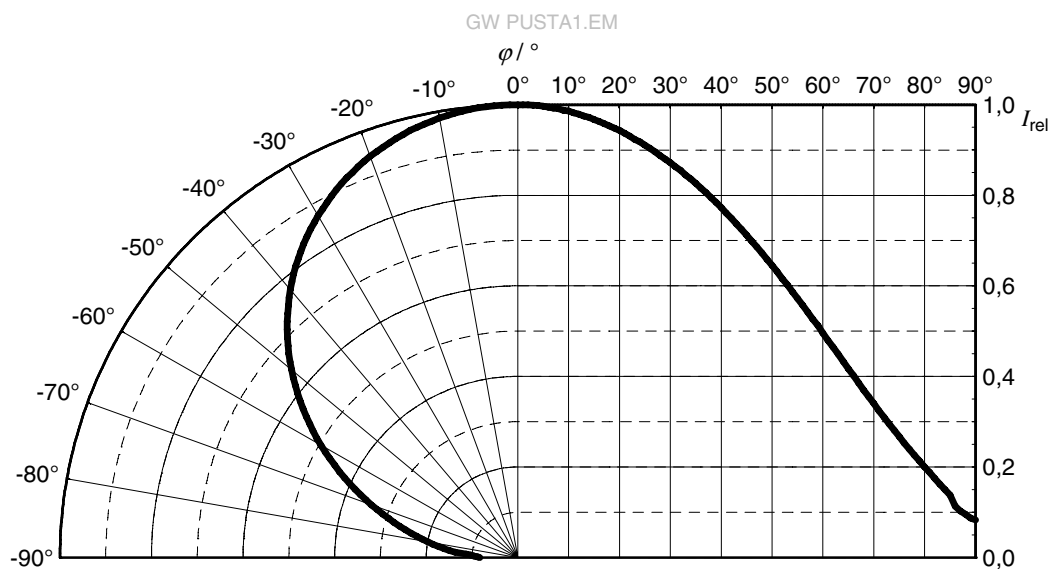
Relative Spectral Emission ⁶⁾

$\Phi_{\text{rel}} = f(\lambda)$; $I_F = 1050 \text{ mA}$; $T_J = 85 \text{ }^\circ\text{C}$



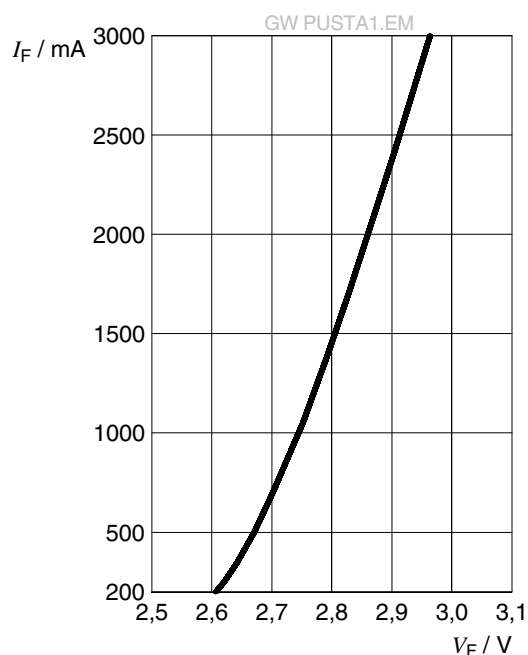
Radiation Characteristics ⁶⁾

$I_{\text{rel}} = f(\phi)$; $T_J = 85 \text{ }^\circ\text{C}$



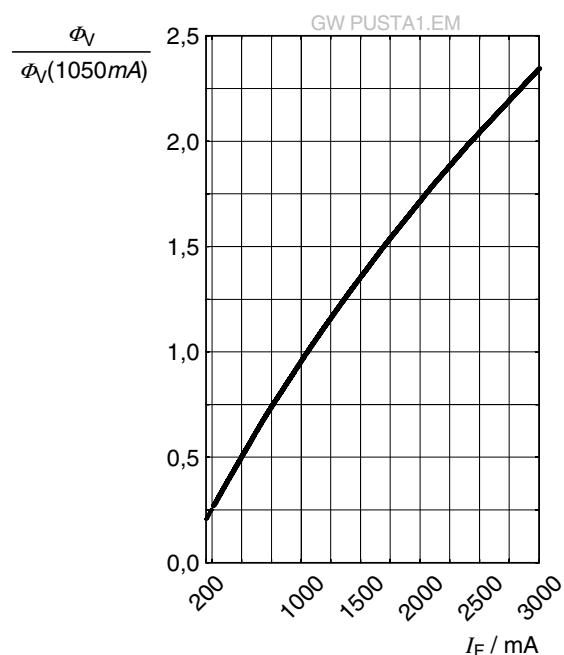
Forward current ⁶⁾

$$I_F = f(V_F); T_J = 85^\circ\text{C}$$



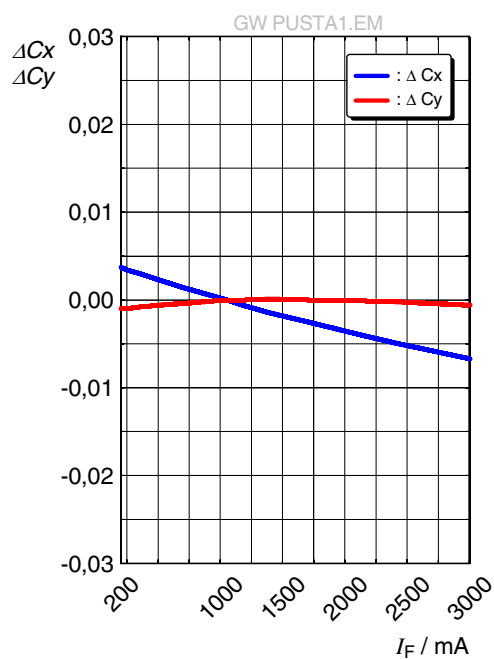
Relative Luminous Flux ^{6), 7)}

$$\Phi_V / \Phi_V(1050 \text{ mA}) = f(I_F); T_J = 85^\circ\text{C}$$



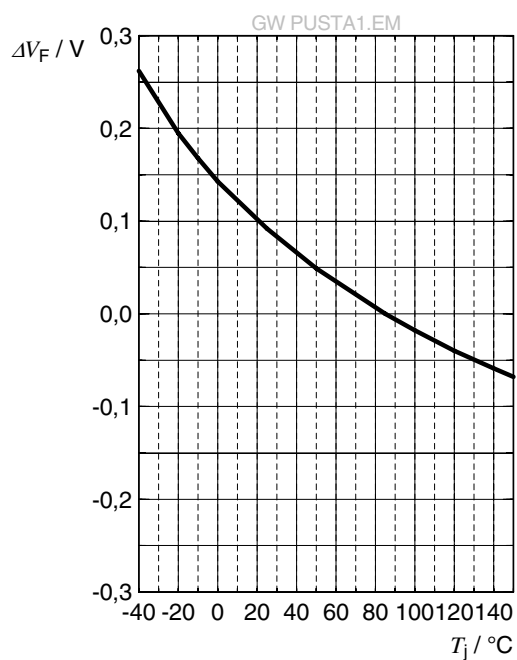
Chromaticity Coordinate Shift ⁶⁾

$$\Delta C_x, \Delta C_y = f(I_F); T_J = 85^\circ\text{C}$$



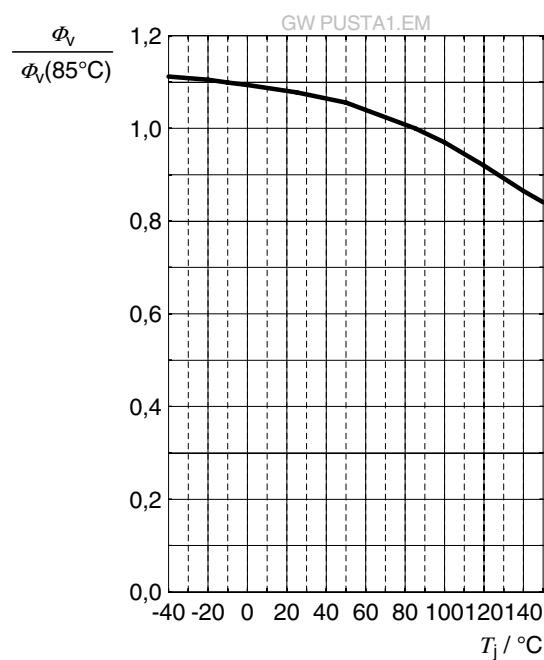
Forward Voltage ⁶⁾

$$\Delta V_F = V_F - V_F(85^\circ\text{C}) = f(T_j); I_F = 1050 \text{ mA}$$



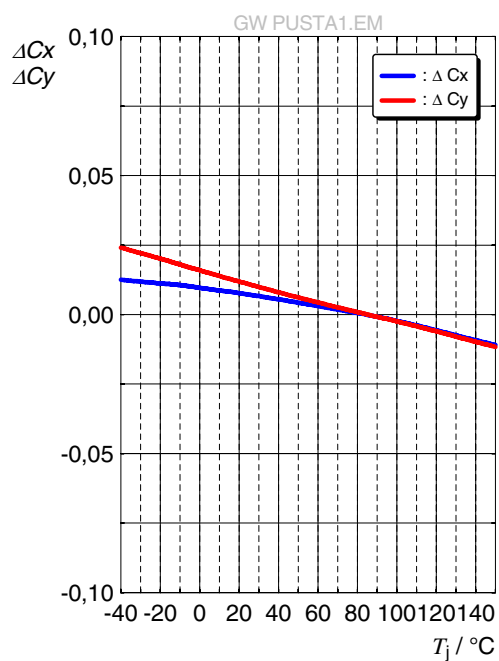
Relative Luminous Flux ⁶⁾

$$\Phi_v / \Phi_v(85^\circ\text{C}) = f(T_j); I_F = 1050 \text{ mA}$$



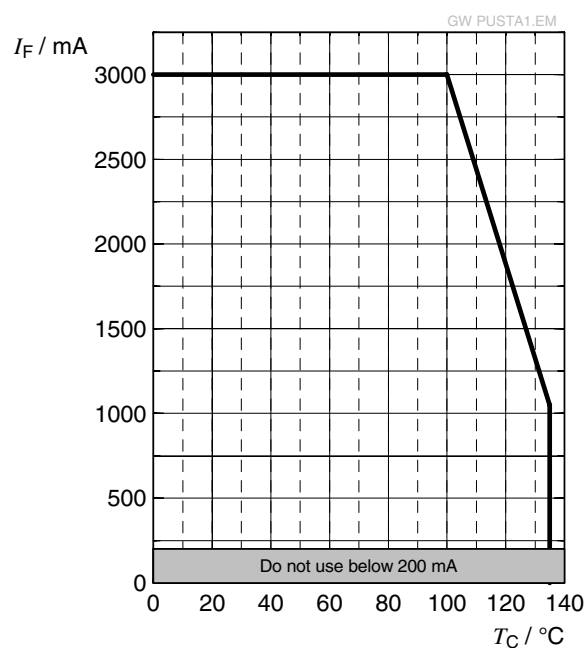
Chromaticity Coordinate Shift ⁶⁾

$$\Delta C_x, \Delta C_y = f(T_j); I_F = 1050 \text{ mA}$$

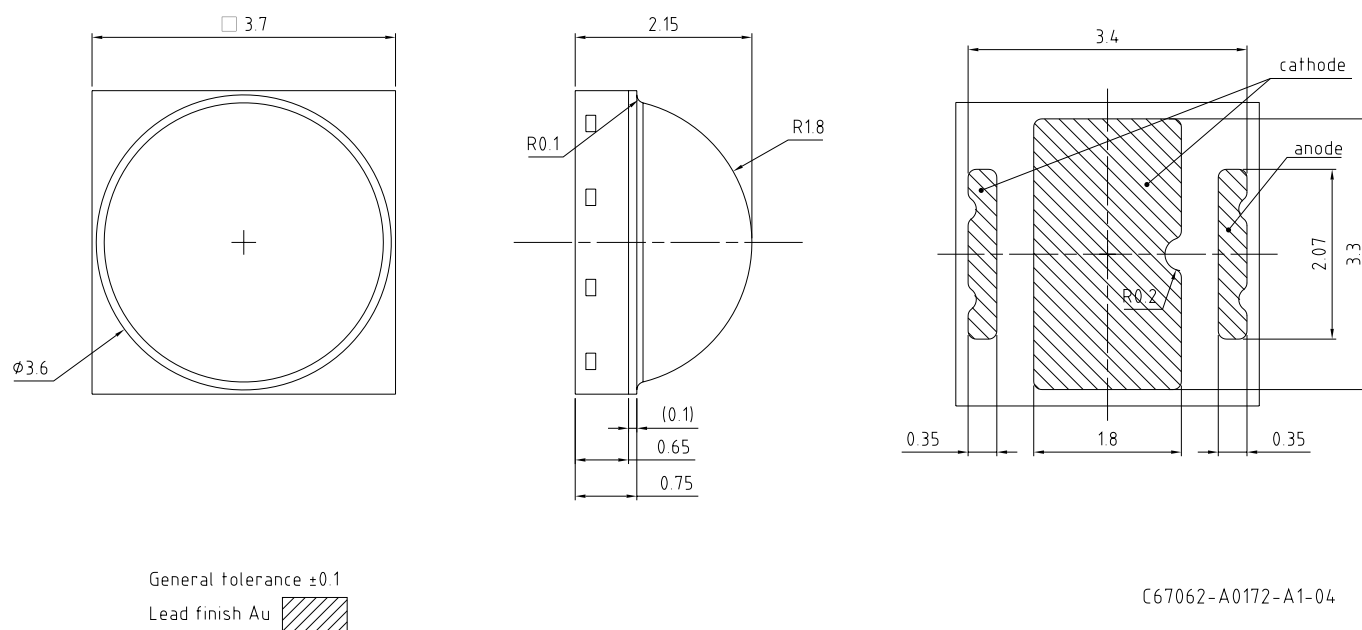


Max. Permissible Forward Current ⁸⁾

$$I_F = f(T)$$



Dimensional Drawing ⁹⁾



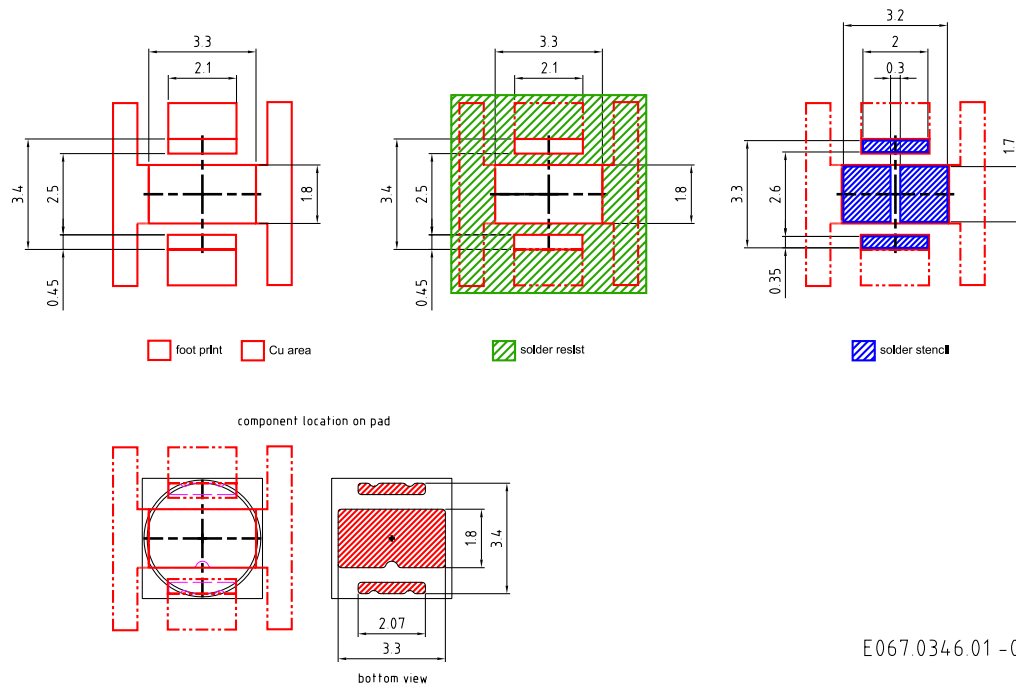
Further Information:

Approximate Weight: 43.0 mg

Package marking: Cathode

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

Recommended Solder Pad ⁹⁾

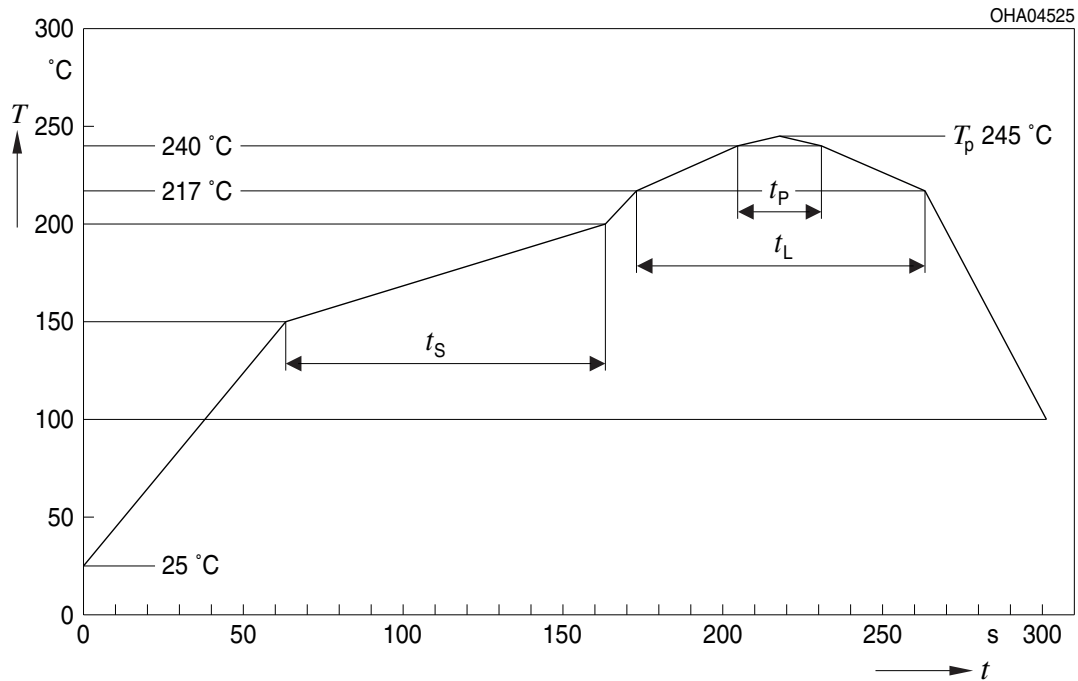


E067.0346.01 -05

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

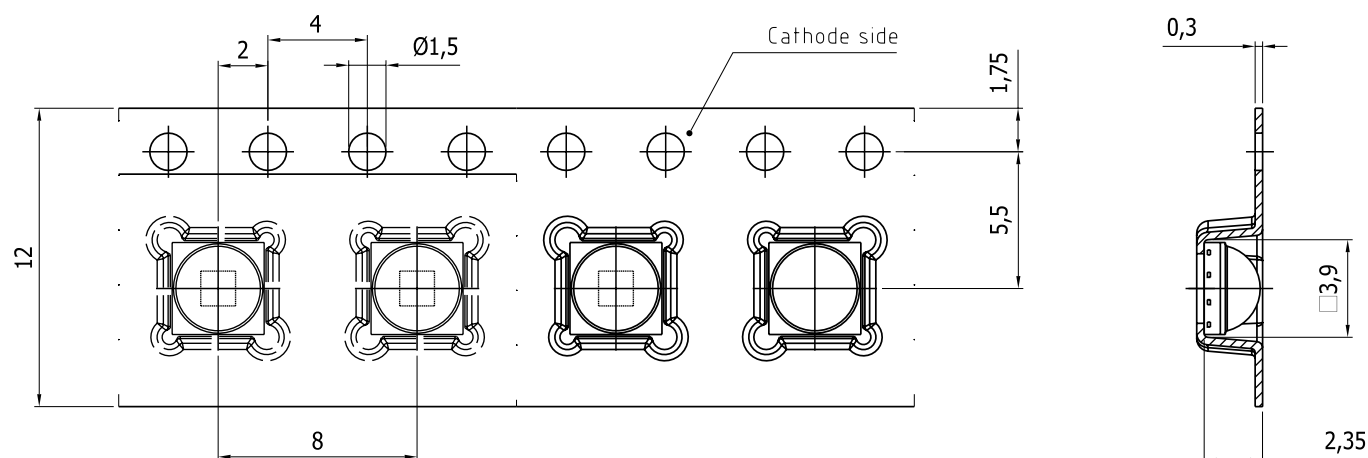


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak ^{*)} T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		$^{\circ}\text{C}$
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	260	$^{\circ}\text{C}$
Time within 5 °C of the specified peak temperature $T_p - 5\text{ K}$	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	6	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component

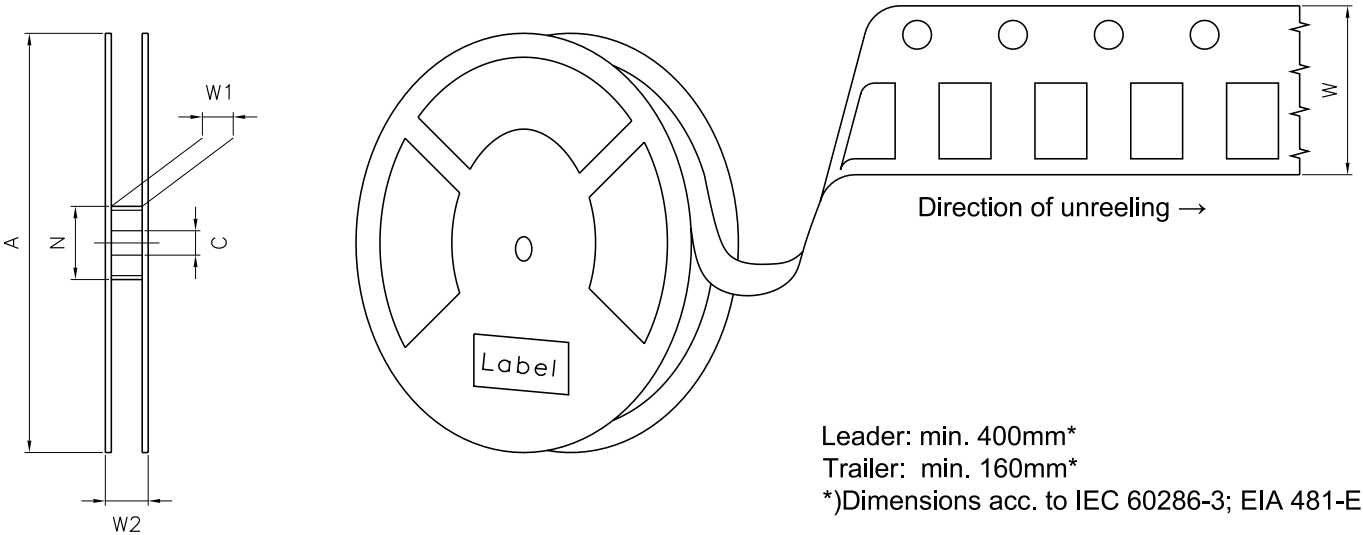
* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping ⁹⁾



C67062-A0172-B11-01

Tape and Reel ¹⁰⁾



Reel Dimensions

A	W	N _{min}	W ₁	W _{2 max}	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	600

Barcode-Product-Label (BPL)

OSRAM

LX XXXX

BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890

(1T) LOT NO: 1234567890

(9D) D/C: 1234

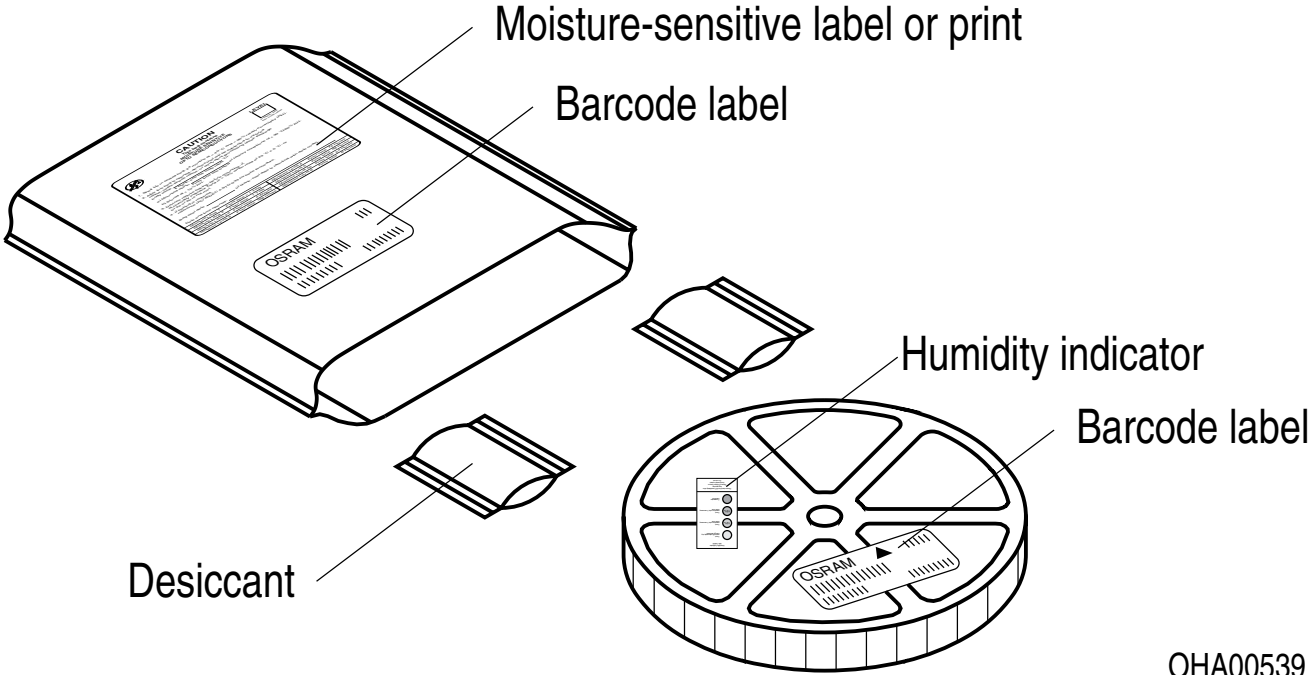
(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

ML Temp ST
X XXX °C X

Pack: RXX
DEMY XXX
X_X123_1234.1234 X

OHA04563

Dry Packing Process and Materials ⁹⁾



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

This device is designed for specific/recommended applications only. Please consult OSRAM Opto Semiconductors Sales Staff in advance for detailed information on other non-recommended applications (e.g. automotive).

Change management for this component is aligned with the requirements of the lighting market.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 10 ms, with a tolerance of +/- 7%.
- 2) **Reverse Operation:** Not designed for reverse operation. Continuous reverse operation can cause migration and damage of the device.
- 3) **Forward Voltage:** The Forward voltage is measured during a current pulse duration of typically 1 ms with a tolerance of $\pm 0.05V$.
- 4) **Color reproduction index:** Color reproduction index values (CRI-RA) are measured during a current pulse of typically 10 ms and with a tolerance of ± 2 .
- 5) **Chromaticity coordinate groups:** Chromaticity coordinate groups are measured during a current pulse duration of typically 10ms with a tolerance of ± 0.005 .
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Thermal Resistance:** $R_{th\ max}$ is based on statistic values (6σ) used for Derating.
- 9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.1	2019-05-03	Ordering Information Disclaimer New Layout
1.2	2020-02-21	Ordering Information Schematic Transportation Box Dimensions of Transportation Box
1.3	2021-06-21	Features Electro - Optical Characteristics (Diagrams)
1.3	2023-02-23	Description
1.4	2023-05-10	Ordering Information Glossary



EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，
不含有毒有害物质或元素。

Published by ams-OSRAM AG

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[NCQB-XX57-1-1050-R33](#) [GW PUSTA1.EM-NCQB-XX56-1-1050-R33](#) [GW PUSTA1.EM-NDQB-XX55-1-1050-R33](#) [GW](#)
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[1050-R33](#)